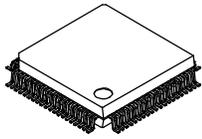


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

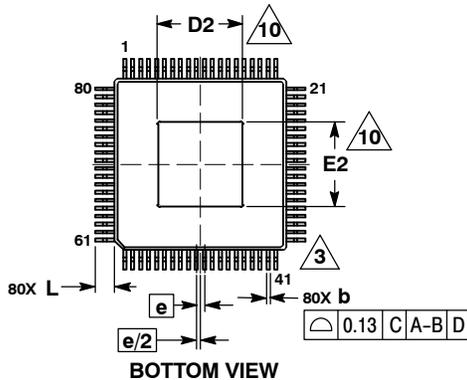
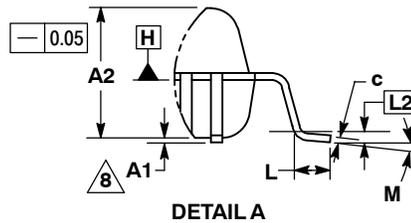
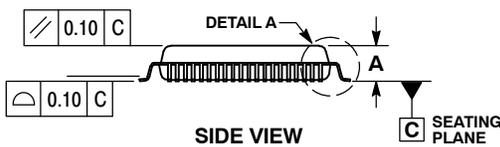
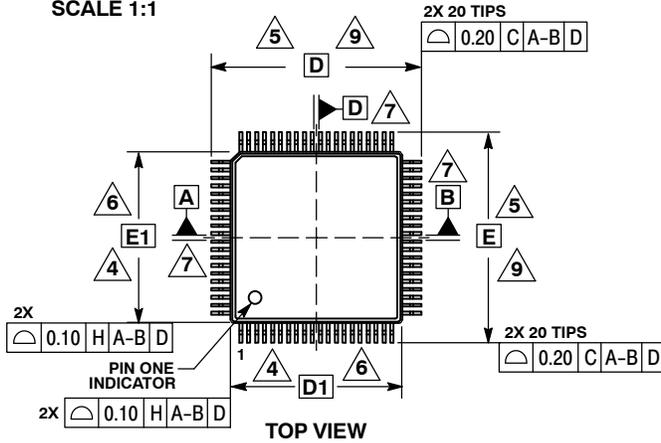
ON Semiconductor®



SCALE 1:1

PQFP80 14x14, 0.65P
CASE 122CG
ISSUE O

DATE 13 MAR 2013

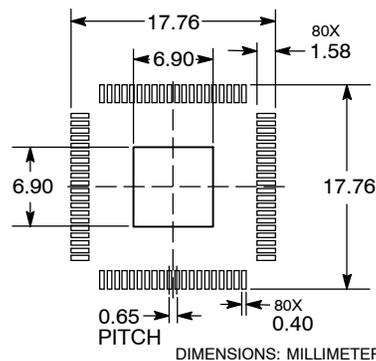


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION *b* DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE 0.08 MAX. AT MMC. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD IS 0.07.
4. DIMENSIONS *D1* AND *E1* DO NOT INCLUDE MOLD FLASH, GATE BURRS, OR PROTRUSIONS. MOLD FLASH, GATE BURRS, OR PROTRUSIONS SHALL NOT EXCEED 0.25 PER SIDE. DIMENSIONS *D1* AND *E1* ARE MAXIMUM PLASTIC BODY SIZE INCLUDING MOLD MISMATCH.
5. THE TOP PACKAGE BODY SIZE MAY BE SMALLER THAN THE BOTTOM PACKAGE SIZE BY AS MUCH AS 0.15.
6. DIMENSIONS *D1* AND *E1* TO BE DETERMINED AT DATUM PLANE H.
7. DATUMS A-B AND D ARE DETERMINED AT DATUM PLANE H.
8. *A1* IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
9. DIMENSIONS *D* AND *E* TO BE DETERMINED AT DATUM PLANE C.
10. EXPOSED PAD TO BE COPLANAR WITH THE BOTTOM OF THE PACKAGE.

DIM	MILLIMETERS	
	MIN	MAX
A	---	2.95
A1	0.05	0.15
A2	2.70	REF
<i>b</i>	0.20	0.30
<i>c</i>	0.10	0.30
D	17.20	BSC
D1	14.00	BSC
D2	6.70	7.10
E	17.20	BSC
E1	14.00	BSC
E2	6.70	7.10
<i>e</i>	0.65	BSC
L	0.60	1.00
L2	0.25	BSC
M	0°	10°

RECOMMENDED
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	PQFP80 14x14, 0.65P	PAGE 1 OF 2

